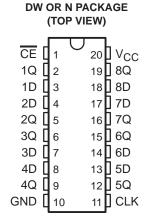
SDFS018D - D2932, MARCH 1987 - REVISED OCTOBER 1993

- Contains Eight D-Type Flip-Flops With Single-Rail Outputs
- Clock Enable Latched to Avoid False Clocking
- Applications Include:

 Buffer/Storage Registers
 Shift Registers
 Pattern Generators
- Buffered Common Enable Input
- Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs



description

The SN74F377A is a monolithic, positive-edge-triggered, octal, D-type flip-flop with clock enable inputs. The SN74F377A features a latched clock enable (CE) input.

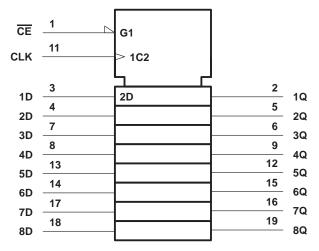
Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if $\overline{\text{CE}}$ is low. Clock triggering occurs at a particular voltage level and is not directly related to the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at the $\overline{\text{CE}}$ input.

The SN74F377A is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

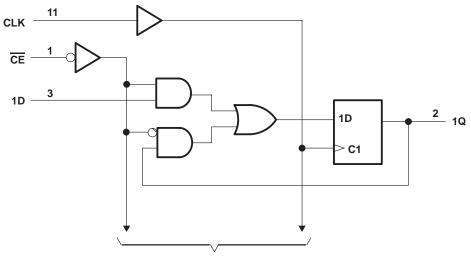
	INPUTS	OUTPUT	
CE	CLK	D	Q
Н	Х	Х	Q ₀
L	\uparrow	Н	Н
L	\uparrow	L	L
Х	L	Х	Q ₀

logic symbol[†]



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	1.2 V to 7 V
Input current range	-30 mA to 5 mA
Voltage range applied to any output in the high state	\dots -0.5 V to V _{CC}
Current into any output in the low state	40 mA
Operating free-air temperature range	0°C to 70°C
Storage temperature range	. −65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input-voltage ratings may be exceeded provided the input-current ratings are observed.



recommended operating conditions

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
ΙK	Input clamp current			- 18	mA
lOH	High-level output current			- 1	mA
loL	Low-level output current			20	mA
TA	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	Т	EST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OH}	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	2.5	3.4		V
VOH	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -1 \text{ mA}$	2.7			V
V _{OL}	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.3	0.5	V
Ι _Ι	$V_{CC} = 0$,	V _I = 7 V			0.1	mA
lін	$V_{CC} = 5.5 V$,	V _I = 2.7 V			20	μΑ
I _{IL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.5 V			- 0.6	mA
I _{OS} ‡	$V_{CC} = 5.5 V$,	V _O = 0	- 60		- 150	mA
^I CCH	$V_{CC} = 5.5 V$,	See Note 2		55	72	mA
ICCL	$V_{CC} = 5.5 V,$	See Note 3		70	90	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements

			V _{CC} :	= 5 V, 25°C	$V_{CC} = 4.5$ $T_A = MIN t$	V to 5.5 V, o MAX§	UNIT
			MIN	MAX	MIN	MAX	
fclock	Clock frequency		0	110	0	110	MHz
t _W	Pulse duration		4		5		ns
	Data high or low	2		2			
t _{su}	Setup time before CLK↑	CE high	2.5		2.5		ns
		CE low	4		4.5		1
4.	Hald Cara of Gara OLIKA	Data high or low	1		1		
th	Hold time after CLK↑ CE high or low				0		ns

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTES: 2. I_{CCH} is measured after applying a momentary ground, then 4.5 V, to the clock input with all data inputs at 4.5 V and the enable input at GND

^{3.} I_{CCL} is measured after applying a momentary ground, then 4.5 V, to the clock input with all data and enable inputs at GND.

SN74F377A OCTAL D-TYPE FLIP-FLOP WITH CLOCK ENABLE SDFS018D – D2932, MARCH 1987 – REVISED OCTOBER 1993

switching characteristics (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)			;, <u>)</u> ,	V _{CC} = 4.5 C _L = 50 pl R _L = 500 Ω T _A = MIN 1	UNIT	
f _{max}			110	125		110		MHz
t _{PLH}	CLK	Any Q	4	6.5	8.5	4	10	
^t PHL	OLK	Ally Q	4	7	9	4	10.5	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 4: Load circuit and waveforms are shown in Section 1.



www.ti.com 24-Jul-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74F377ADW	Obsolete	Production	SOIC (DW) 20	-	-	Call TI	Call TI	0 to 70	F377A
SN74F377ADWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F377A
SN74F377ADWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F377A
SN74F377ADWR.B	Active	Production	SOIC (DW) 20	2000 LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	0 to 70	F377A
SN74F377AN	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F377AN
SN74F377AN.A	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F377AN

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

www.ti.com 24-Jul-2025

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F377ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025



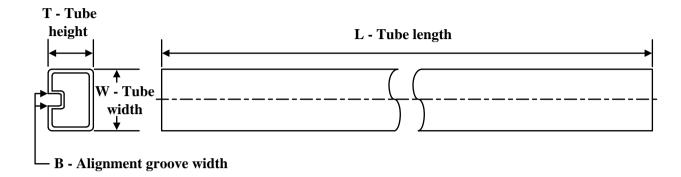
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74F377ADWR	SOIC	DW	20	2000	356.0	356.0	45.0	

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74F377AN	N	PDIP	20	20	506	13.97	11230	4.32
SN74F377AN.A	N	PDIP	20	20	506	13.97	11230	4.32

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2025. Texas Instruments Incorporated